Product Change Notification: MAAN-10SXHP968

Date:

17-Sep-2026

Product Category:

Depletion Mode Mosfets, N-Channel Enhancement Mode Mosfets, P-Channel Enhancement Mode Mosfets

Notification Subject:

CCB 8332 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 2N7002-G, DN1509T-V/C6X, DN3135K1-G, LND150K1-G, LND250K1-G, TN2106K1-G, TN2124K1-G, TN2124K1-G-D545, TN2130K1-G, TN5325K1-G, TN5335K1-G, TN5335K1-G-D589, TP0610T-G, TP2104K1-G, TP5322K1-G, TP5335K1-G, TP5335K1-G-AAA, TP5335K1-G-D588, VN2110K1-G, VP2110K1-G and VP2110K1-G-D537 catalog part numbers (CPN) available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Affected CPNs:

MAAN-10SXHP968_Affected_CPN_09172026.pdf
MAAN-10SXHP968_Affected_CPN_09172026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 2N7002-G, DN1509T-V/C6X, DN3135K1-G, LND150K1-G, LND250K1-G, TN2106K1-G, TN2124K1-G, TN2124K1-G-D545, TN2130K1-G, TN5325K1-G, TN5335K1-G, TN5335K1-G-D589, TP0610T-G, TP2104K1-G, TP5322K1-G, TP5335K1-G, TP5335K1-G-AAA, TP5335K1-G-D588, VN2110K1-G, VP2110K1-G and VP2110K1-G-D537 catalog part numbers (CPN) available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change

			(Yes/No)
Assembly Site	Microchip Technology Thailand (MTAI)	Microchip Technology Thailand (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8060T (PFAS-free)	8060T (PFAS-free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 14 October 2026 (date code: 2642)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	**September 2026**				**October 2026**				
Work Week	23	24	25	26	27		36	37	38	39	40	41	42	43	44
Initial PCN Issue Date			X												
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date													X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 15, 2026: Issued initial notification.
September 17, 2026: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on October 14, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MAAN-10SXHP968_Qualification Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

TN2130K1-G

TN5325K1-G

TN5335K1-G

TN5335K1-G-D589

TP0610T-G

TP2104K1-G

TP5322K1-G

TP5335K1-G

TP5335K1-G-AAA

TP5335K1-G-D588

VN2110K1-G

VP2110K1-G

VP2110K1-G-D537

2N7002-G

DN1509T-V/C6X

DN3135K1-G

LND150K1-G

LND250K1-G

TN2106K1-G

TN2124K1-G

TN2124K1-G-D545



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: MAAN-10SXHP968

Date

September 3, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 2N7002-G, DN1509T-V/C6X, DN3135K1-G, LND150K1-G, LND250K1-G, TN2106K1-G, TN2124K1-G, TN2124K1-G-D545, TN2130K1-G, TN5325K1-G, TN5335K1-G, TN5335K1-G-D589, TP0610T-G, TP2104K1-G, TP5322K1-G, TP5335K1-G, TP5335K1-G-AAA, TP5335K1-G-D588, VN2110K1-G, VP2110K1-G and VP2110K1-G-D537 catalog part numbers (CPN) available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 2N7002-G, DN1509T-V/C6X, DN3135K1-G, LND150K1-G, LND250K1-G, TN2106K1-G, TN2124K1-G, TN2124K1-G-D545, TN2130K1-G, TN5325K1-G, TN5335K1-G, TN5335K1-G-D589, TP0610T-G, TP2104K1-G, TP5322K1-G, TP5335K1-G, TP5335K1-G-AAA, TP5335K1-G-D588, VN2110K1-G, VP2110K1-G and VP2110K1-G-D537 catalog part numbers (CPN) available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

CN:	E000313632
QUAL ID:	R2600768
QUAL ID Rev.:	A
MP CODE:	6H002QC6XD00
Part No.:	TP5335K1-G
Bonding No.:	BD-004443-02
CCB No.:	8332

Lead Frame

Paddle Size:	64x38 mils
Material:	CDA194
DAP Surface Prep:	Ag Spot Plating
Treatment:	None
Process:	Stamped
Part Number:	10100301
Lead Plating:	Matte Tin
Strip Size:	228.288x50.800mm
Strip Density:	256units/strip

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	8060T
Conductive:	Yes

Mold Compound

Material:	G600V

Package

Type:	3L SOT-23
Package Size:	1.3mm

Manufacturing Information

Assembly Lot No.
MTAI271202335.000
MTAI271301219.000
MTAI271301220.000

Result: Pass

Conclusion:

Qualification of 6H002 mask / TP5335K1-G product / CuPdAu wire in 3L SOT-23 1.3mm package at MTAI site is qualified for MSL1 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result
Moisture Soak Precondition Prior to Stresses	**MSL1:** 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C **Electrical Test Tester:** ETS300_HV 25°C and 150°C	JESD22-A113 , JEDEC J-STD-020	231 units each lot / 3 lots	0/231, 0/231, 0/231	Pass
High Temp Storage	175°C / 504 hours **Electrical Test Tester:** ETS300_HV 25°C and 150°C	JESD22-A103	45 units / 3 lot	0/45, 0/45, 0/45	Pass
Temperature Cycling	-65°C / +150°C Air to Air / 500 Cycles **Electrical Test Tester:** ETS300_HV 150°C	JESD22-A104	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass
	Wire Bond Pull after Temperature Cycling		5 units	0/5	Pass
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 20.0V **Electrical Test Tester:** ETS300_HV 25°C and 150°C	JESD22-A110	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass
Unbiased HAST	+130°C / 85%RH / 96 hours **Electrical Test Tester:** ETS300_HV 25°C	JESD22-A118	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q1 00-001	5 units / 1 lot	0/5	Pass